

PRODUCT DATA SHEET

SikaBond®-54 Parquet

PREMIUM, ELASTIC, LOW VISCOUS WOOD FLOORING ADHESIVE

PRODUCT DESCRIPTION

SikaBond®-54 Parquet is a 1-component, solvent-free, wood flooring adhesive with very good workability.

USES

SikaBond®-54 Parquet is designed for full surface bonding of solid and engineered wood floors, mosaic parquet, industrial parquet, lam parquet, residential wood floors and paving, as well as chipboard floor systems and subfloors. SikaBond®-54 Parquet is designed for use with most common types of wood floors and is especially designed for use with challenging woods Please note:

The Product may only be used for interior applications.

CHARACTERISTICS / ADVANTAGES

- Adhesive can be sanded
- Economical, low consumption
- Elastic, footfall-sound dampening properties
- Floor can be sanded after 12 hours
- Good workability
- Reduces stress transfer between the wood floor and the substrate
- Suitable for bonding directly on old ceramic tiles
- Very low emissions
- Suitable for use with underfloor heating

ENVIRONMENTAL INFORMATION

- VOC emission classification GEV-Emicode EC1^{PLUS}, license number 3143/01.01.21
- LEED v4 EQc 2: Low-Emitting Materials

PRODUCT INFORMATION

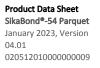
Chemical Base	i-Cure® technology polyurethane	
Packaging	13 kg container / 6.5 kg metal pail 700 ml foil	
Shelf Life	SikaBond®-54 Parquet has a shelf life of 12 months from the date of production, if it is stored properly in undamaged, original, sealed packaging, and if the storage conditions are met.	
Storage Conditions	SikaBond®-54 Parquet shall be stored in dry conditions, protected from direct sunlight and at temperatures between +5 °C and +25 °C.	
Colour	Beige	
Density	~1.30 kg/l	(ISO 1183-1)
TECHNICAL INFORMATION		
Shore A Hardness	~35 (after 28 days)	(ISO 868)
Tensile Strength	~1.5 N/mm²	(ISO 37)

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Elongation at Break	~500 %	(ISO 37)
Shear Strength	~1.5 N/mm² (1 mm adhesive thickness)	(ISO 17178)
Service Temperature	+5 °C min. / +40 °C max.	

APPLICATION INFORMATION

Consumption	Note: When bonding long or wide boards or applying on uneven substrates, a sufficient amount of adhesive must be applied to provide full surface bonding. Note: Substrates primed with Sika® Primer MB, may reduce the consumption.		
	Consumption (Full surface bonding)	V-notched trowel type (TKB Ger- many)	
	600-800 g/m ²	Trowel B3	
	700–900 g/m ²	Trowel B6	
	800–1000 g/m ²	Trowel B11 (P5 (US Standard))	
Sag Flow	due to surface porosity, surface profile, variations in level, wastage or an other variations. Apply product to a test area to calculate the exact consumption for the specific substrate conditions and proposed application equipment.		
Sag Flow	Spreads very easily whilst maintaining stable trowel peaks.		
Ambient Air Temperature	+15 °C min. / +35 °C max.		
Relative Air Humidity	40 % min. / 70 % max.		
Substrate Temperature	During laying and until SikaBond®-54 Parquet has fully cured, the substrate and ambient temperatures shall be between +15 °C and +35 °C without and between +20 °C and +35 °C with underfloor heating		
Curing Time	~4.0 mm/24 hours (23 °C / 50 % r.h.)		
	~60 minutes (23 °C / 50 % r.h.)		







VALUE BASE

All technical data stated in this Data Sheet are based on laboratory tests. Actual measured data may vary due to circumstances beyond our control.

FURTHER DOCUMENTS

- Safety Data Sheet
- Pre-treatment Chart Sealing and Bonding
- Method Statement "Full Surface Bonding"

LIMITATIONS

- SikaBond®-54 Parquet is only suitable for use by professional wood floor applicators.
- Substrate moisture content measurements alone are not a sufficient basis for the wood flooring installer to decide on readiness for covering. Other tests must be considered as mentioned for existing cementitious sub-floors and new screeds. Tests must be appropriate to the type of floor covering, composition, behaviour of existing sub-floor, new screed and job site ambient conditions.
- The surface of the substrate must meet the strength requirements of the wood flooring manufacturer. Testing the tensile strength of the substrate alone is not sufficient to assess the surface condition. Additional criteria such as roughness, absorbency and cleanliness must also be evaluated. For wood floor bonding, a minimal tensile strength of ≥ 1 N/mm² is required (according to EN 13892-8). New mastic asphalt (fully broadcasted) must meet the requirements of IC 10 or IC 15 (DIN 18 354 and DIN 18 560). Old mastic asphalt must in every case be tested in several floor locations and evaluated by a specialist laboratory.
- If there is any doubt the floor substrate cannot satisfy the moisture or surface conditions, the installation must not progress. Alternative floor products that can improve the substrate conditions must be considered such as surface hardeners or thin layer overlays. Contact Sika Technical Services for additional information.
- For good workability, the adhesive temperature shall be ≥ +15 °C.
- For proper curing of the adhesive, sufficient ambient humidity / moisture is necessary.
- A preliminary adhesion test is necessary before any application on glazed tiles.
- For use with chemically pre-treated types of wood floors (e.g. those produced or treated with ammonia, wood stain, timber preservative) and woods with a relatively high oil content, SikaBond®-54 Parquet is only to be used with the written agreement of Sika Technical Service.
- Do not use on polyethylene (PE), polypropylene (PP), polytetrafluoroethylene (PTFE / Teflon), and other similar plasticized synthetic materials.
- Incompatible floor primers can negatively influence the adhesion the Product. Preliminary trials must be carried out before using for full application.
- SikaBond®-54 Parquet is designed as a wood floor bonding adhesive. When laying parquet type wood floors without tongued and grooved joints, e.g. mo-

- saic parquet floors, avoid the wood floor adhesive extruding into the joints between the wood pieces.
- Avoid contact between any wood surface sealer coatings and adhesive. However, if direct contact with the adhesive is unavoidable, then the compatibility must be checked and confirmed before use of any coatings. For further information and advice contact Sika Technical Service.
- Do not expose uncured SikaBond®-54 Parquet to alcohol containing products as they may interfere with the curing reaction.

ECOLOGY, HEALTH AND SAFETY

User must read the most recent corresponding Safety Data Sheets (SDS) before using any products. The SDS provides information and advice on the safe handling, storage and disposal of chemical products and contains physical, ecological, toxicological and other safety-related data.

Regulation (EC) No 1907/2006 (REACH) - Mandatory training

As from 24 August 2023 adequate training is required before industrial or professional use of this product. For more information and a link to the training visit www.sika.com/pu-training.



APPLICATION INSTRUCTIONS

For the application of SikaBond®-54 Parquet all generally accepted rules for wood flooring installation apply.

For further information, please refer to the Method Statement "Full Surface Bonding".

SUBSTRATE PREPARATION

Note: Adhesion tests on project specific substrates must be performed and procedures agreed with all parties before full project application. For more detailed advice and instructions contact Sika Technical Services

- The substrate must be clean, dry, sound and free from oils, grease, dust, cement laitance and loose or friable particles.
- Use wire brushing, abrading, grinding or grit blasting equipment to prepare the substrate.

Completely remove all dust, loose and friable material from all surfaces before application of any activators, primers or adhesive preferably by industrial vacuuming equipment.



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Concrete / cementitious screeds

Grind flat the substrate to provide a smooth surface without any surface irregularities.

Fill any voids or cavities with appropriate Sika® compatible flooring repair or levelling products.

Calcium sulphate (Anhydrite) screeds

Grind flat the substrate to provide a smooth surface without any surface irregularities.

Fill any voids or cavities with appropriate Sika® compatible flooring repair or levelling products.

Mastic asphalt

Prime with Sika® Primer MB and broadcast with quartz sand. Refer to individual Product Data Sheets.

Glazed or unglazed ceramic tiles

Degrease and clean with Sika® Aktivator-205. Alternatively grind glazed surfaces to remove the glaze.

Wood

Note: Wood types such as chipboards (V100), OSB or plywood as well as gypsum boards must be securely fixed to the substructure.

Note: For floating dry floors, contact Sika Technical Services for additional information.

Remove any surface irregularities using abrading equipment.

Other substrate types

Contact Sika Technical Services.

Priming

The Product can be used without priming on concrete / cementitious/ anhydrite screeds, chipboards, concrete and ceramic tiles.

Use Sika® Primer MB for broadcasted mastic asphalt, concrete / cementitious subfloors or screeds with excessive moisture content, old adhesive residue or weak substrates. Refer to individual Product Data Sheet or contact Sika Technical Services for additional information.

Before wood floors can be installed in non-insulated areas, such as basements or other areas without a damp proof membrane, Sikafloor®EpoCem must be applied and sealed with Sika®Primer MB to control the moisture. Contact Sika Technical Services for additional information.

APPLICATION METHOD / TOOLS

Strictly follow installation procedures as defined in method statements, application manuals and working instructions which must always be adjusted to the actual site conditions.

Existing sub-floors

The sub-floor must be ready for covering at time of installation of the wood flooring to prevent adhesive adhesion failure. It is the responsibility of the wood flooring installer to confirm the sub-floor is acceptable for laying the specific type of wood flooring. The installation area's ambient conditions must also be

taken into consideration with regard to the effect on the sub-floor and wood flooring. Sub-floor and timber moisture content readings together with the installation area's air humidity conditions must be satisfied before the wood flooring installation.

New screeds

Screeds must be ready for covering at time of installation of the wood flooring to prevent adhesive adhesion failure. It is the responsibility of the wood flooring installer to confirm the screed is acceptable for laying the specific type of wood flooring. The installation area's ambient conditions must also be taken into consideration with regard to the effect on the new screed and wood flooring.

New screed and timber moisture content readings together with the installation area's air humidity conditions must be satisfied before the wood flooring installation. Acceptability must also be confirmed after consultation with the customer and if necessary, also with the assistance of the screed installer.

Wood flooring conditioning

Condition the wood flooring in the area where it is to be installed in accordance with the manufacturer's recommendations.

Adhesive application Full surface bond

1. Spread the Product uniformly over the substrate with a V-notched trowel or spreader comb directly from the product container.

Laying wood flooring

Note: Refer to wood flooring manufacturer's recommendations for expansion gap locations and dimensions.

- Press the wood floor pieces firmly into the adhesive so the wood floor underside is completely covered with the adhesive.
- Adjust the pieces into position using a rubber hammer and an impact block.
- 3. To make sure of full contact between adhesive and the underside of the wood flooring, weigh down the flooring with weights such as sandbags or full boxes of uninstalled wood flooring.

Cleaning

Note: Always test wood floor surfaces for compatibility with Sika® Remover-208 before use.

Note: Reference must also be made to the wood flooring manufacturers cleaning recommendations.

- 1. Remove immediately, fresh, uncured adhesive from the wood floor surface with a clean cloth.
- 2. If necessary, also clean with Sika® Remover-208.

Sanding and finishing

The floor must not be walked on earlier than 24 hours. Sanding or mechanical polishing can be carried out when curing times have been achieved. Refer to curing times.





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CLEANING OF TOOLS

Clean all tools and application equipment immediately after use with Sika® Remover-208. Once cured, residual material can only be removed mechanically.

LOCAL RESTRICTIONS

Note that as a result of specific local regulations the declared data and recommended uses for this product may vary from country to country. Consult the local Product Data Sheet for exact product data and uses.

LEGAL NOTES

The information, and, in particular, the recommendations relating to the application and end-use of Sika products, are given in good faith based on Sika's current knowledge and experience of the products when properly stored, handled and applied under normal conditions in accordance with Sika's recommendations. In practice, the differences in materials, substrates and actual site conditions are such that no warranty in respect of merchantability or of fitness for a particular purpose, nor any liability arising out of any legal relationship whatsoever, can be inferred either from this information, or from any written recommendations, or from any other advice offered. The user of the product must test the product's suitability for the intended application and purpose. Sika reserves the right to change the properties of its products. The proprietary rights of third parties must be observed. All orders are accepted subject to our current terms of sale and delivery. Users must always refer to the most recent issue of the local Product Data Sheet for the product concerned, copies of which will be supplied on request.

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